

KIOXIA Corporation

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PHONE: 81-45-890-2538

Date: July 14th, 2021

Ref. No.: 21MQ-G005-1(E)

To: _____

Product Change Notification

This letter is to inform you of the following changes.

1. Affected products

Product type: 24nm 4Gbit 4-stack SLC NAND TSOP-packaged products

Part number: TH58NVG4S0HTA20, TH58NVG4S0HTAK0

2. Reason for change

To enhance the production capability and for stable supply of products.

3. Change description

The lead frame processing method will be changed from etching to stamping.

The changed lead frame has been used in other products.

There is no change of lead frame supplier, structure, environmental data, and the specification of the products.

4. Change schedule

Production using the changed Lead frame is targeted to start from January 2022 (running change).

5. Reliability data

Moisture Resistance Test (MRT), Highly Accelerated Stress Test (HAST) and Temperature Cycling (TC) results showed no failures. For reliability test data, please see the attached file.

6. Evaluation samples

Evaluation samples are available.

If you need evaluation samples, please place an order by August 13th, 2021.**7. Method to identify changed products**

You can identify the change by the additional code that is printed on the labels.

	Additional Code
Current Product	B4M or B4H
Changed Product	B4A

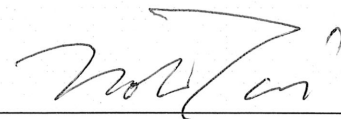
8. Customer responsePlease acknowledge above and send your acceptance notification by September 30th, 2021.

If we do not your receive response by the above date, we will deem this change accepted.

If you have any inquiry of this subject, please contact our sales representatives.

We appreciate your understanding and cooperation.

Sincerely,



Nobuyuki Tai

Group Manager

Memory Customer Quality Engineering Group

Memory Q&R Engineering Department

KIOXIA Corporation